

TK39N60W5-VB Datasheet

N-Channel 600V (D-S) Super Junction Power MOSFET

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	600)
R _{DS(on)} at 25 °C (Ω)	$V_{GS} = 10 V$	0.060

FEATURES

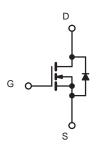
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting



TO-247



N-Channel MOSFET

Top View

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V _{DS}	600	v	
Gate-Source Voltage		V _{GS}	± 30	v	
Continuous Drain Current (T. 150 °C)	$V_{GS} \text{ at } 10 \text{ V} $ $T_{C} = 25 ^{\circ}\text{C} $ $I_{D} $ 47 $T_{C} = 100 ^{\circ}\text{C} $ 29				
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	V _{GS} at 10 V	T _C = 100 °C	ID	29	A
Pulsed Drain Current ^a	Drain Current ^a		I _{DM}	140	
Linear Derating Factor				1.67	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	850	mJ
Maximum Power Dissipation			PD	510	W
Operating Junction and Storage Temperature Range	e		T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	Itage Slope $T_J = 125 \text{ °C}$ 50				
Reverse Diode dV/dt ^d		dV/dt	15	V/ns	
Soldering Recommendations (Peak Temperature) ^c	for	10 s		260	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD} = 100 \text{ V}$, starting $T_J = 25 \text{ °C}$, L = 30mH, $R_g = 25 \Omega$, $I_{AS} = 24A$.

c. 1.6 mm from case. d. $I_{SD} \le I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

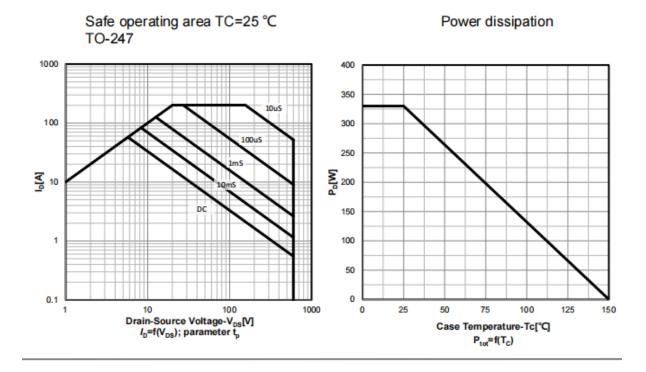


THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-		62			°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-		0.3	8		C/W	
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	nless otherw	ise noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNI
Static		-						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D =	1 mA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	, I _D = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2.5	-	4.5	V
			$V_{GS} = \pm 20$) V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30$) V	-	-	± 1	μA
		V _{DS} =	$V_{DS} = 600V, V_{GS} = 0V$ 1					
Zero Gate Voltage Drain Current	I _{DSS}	-		V, T _J = 125 °C	-	-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	1	I _D =16A	-	0.060	-	Ω
Forward Transconductance		V _{DS}	_s = 30 V, I _D	= 16 A	-	5.6	-	S
Dynamic						<u> </u>		
Input Capacitance	C _{iss}		V _{GS} = 0 \	1	-	4900	-	
Output Capacitance	Coss		$V_{\rm DS} = 0.0$ $V_{\rm DS} = 100$		-	330	-	1
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		4	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}		(to 500 V		-	63	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$V_{DS} = 0 V \text{ to } 520 V, V_{GS} = 0 V$		-	213	-		
Total Gate Charge	Qg				-	370	-	nC
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	$I_{\rm D} = 20$	0 A, V _{DS} = 520 V	-	39	-	
Gate-Drain Charge	Q _{gd}				-	47	-	
Turn-On Delay Time	t _{d(on)}				-	18	25	
Rise Time	t _r	V _{DD}	= 520 V, I _D	₀ = 20A,	-	24	55	ns
Turn-Off Delay Time	t _{d(off)}	Ves	= 10 V, R _q	= 9.1 Q	-	80	-	
Fall Time	t _f		0		-	12	-	
Gate Input Resistance	Rg	f = 1	MHz, ope	n drain	-	0.8	-	Ω
Drain-Source Body Diode Characteristic	S							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	47	A	
Pulsed Diode Forward Current	I _{SM}			-	-	140		
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 8 A, V _{GS} = 0 V		-	-	1.5	V	
Reverse Recovery Time	t _{rr}		-	-	-	520	-	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 2$	25 °C, I _F =	$I_{\rm S} = 8 {\rm A},$	-	5.8	-	μC
Reverse Recovery Current	I _{RRM}	dl/dt = 1	ιυυ Α/μs, \	$V_{\rm R} = 400 \rm V$	-	4 5		A

Notes

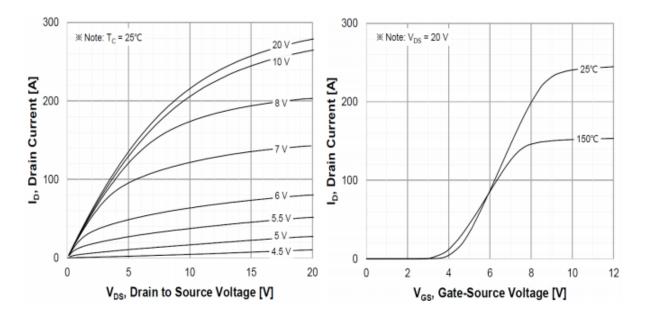
a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



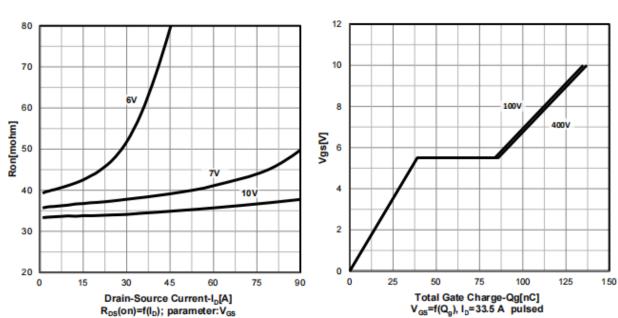


Typ. output characteristics T_i =25 $^{\circ}C$

Transfer characteristics



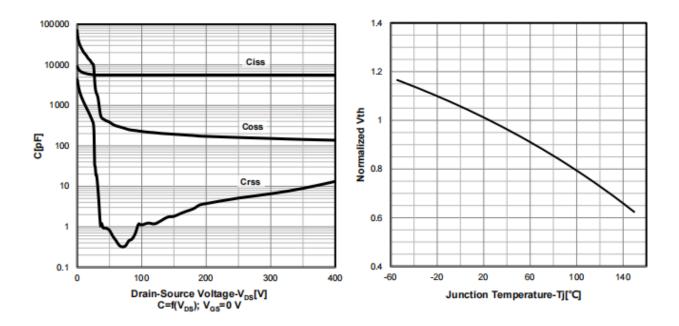




Typ. drain-source on-state resistance

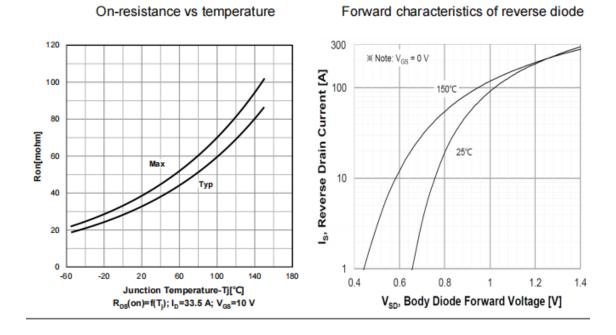
Typ. capacitances

Normalized $V_{GS(th)}$ characteristics



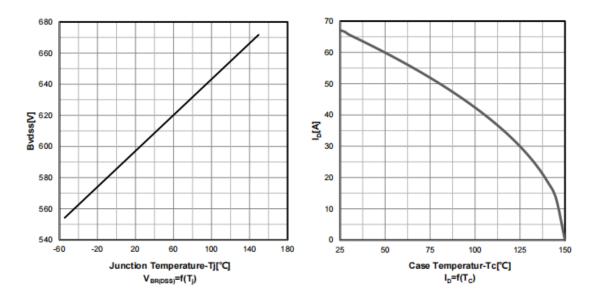
Typ. gate charge characteristics





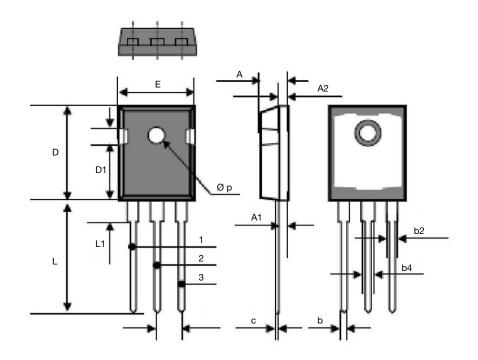
Drain-source breakdown voltage

Drain current vs temperature





TO-247



DIM.	MILLIN	METERS	INC	HES	
	MIN.	MAX.	MIN.	MAX.	
А	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61 BSC		0.024 BSC		
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46 BSC		0.215 BSC		
E	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øp	3.51	3.66	0.138	0.144	



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